

FANCO PRECISION (M) SDN BHD



FANCO PRECISION (M) SDN. BHD.

FANCO PRECISION, established since year 2004, the pre-eminent vendor in supplying customized precision parts & electronic devices majorly to semiconductor companies, particularly on transfer parts, trim & form tooling, automation system, mold equipment, inspection equipment and electronic items.

Over the years, we are specialized and focused to cater to the demand of semiconductor equipment & parts sourcing solutions.

FANCO PRECISION is proudly certified to meet the internationally recognized Quality Management System of ISO 9001:2015. In line with our certification, We are always passionate and ready to provide excellent reliable quality products or services and providing competitive values to you!

Company Information



30 & 32, PERSIARAN PERINDUSTRIAN PENGKALAN 8, KAWASAN PERINDUSTRIAN PENGKALAN, 31500 IPOH, PERAK, MALAYSIA.



+605 - 321 2108 +6019 - 513 8318



https://www.fanco-precision.com/





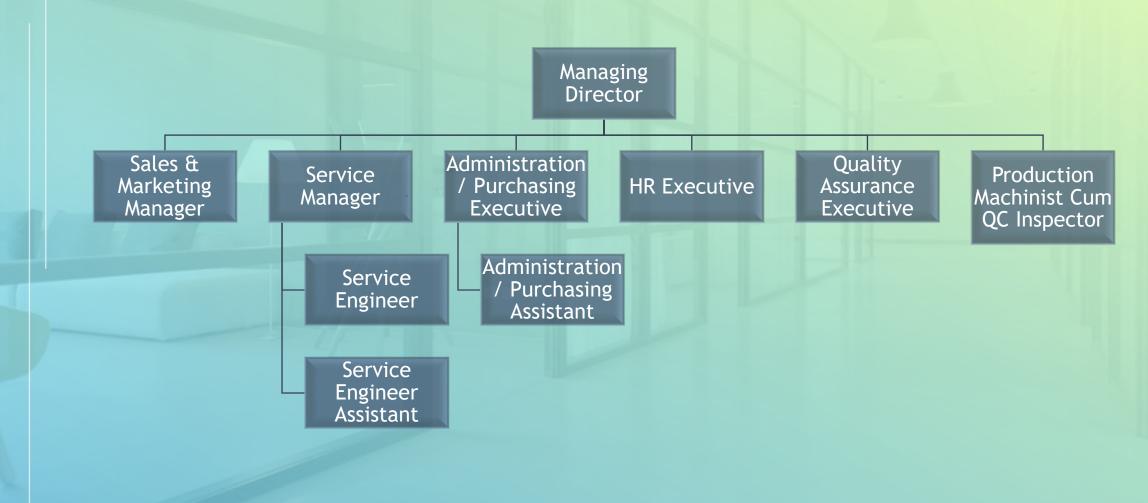
ymfan@fanco-precision.com jessypong@fanco-precision.com fancoprecision@gmail.com



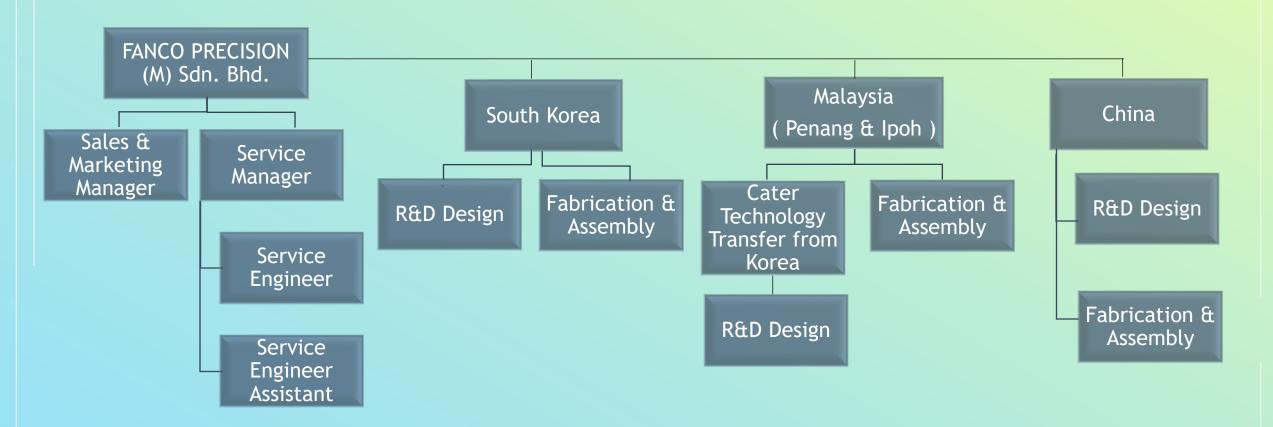
ISO 9001: 2015 Certified Company



Organization Chart



Our Technology Partners



Quality Policy

FANCO PRECISION is committed to unveiling customers' requirements, thereby satisfying them by achieving total customer satisfaction and surpassing their expectations so as to our partnership with our vendors and employees. In any collaboration, we always work together to deliver cost competitive, high quality, reliable products and excellence service to you!

Our Vision, Mission & Value



✓ To be customer's obvious choice by providing highly trusted and satisfied technology products and solutions.



- ✓ Highly Reliable Products
- ✓ Outstanding And Reliable Quality Products / Solutions
- ✓ Competitive Pricing
- ✓ Excellent Services
- ✓ Achieve Goals With Confidence And Assertiveness



- ✓ Excellence In Quality & Service
- ✓ Passion For Perfection
- ✓ Total Customer Satisfaction
- ✓ Respect
- ✓ Caring
- ✓ Collaboration

Vision Mission

Corporate Value

ISO 9001: 2015 Certificate



Certification is conditional on maintaining the required performance standards throughout the certified period of registration.

The British Assessment Bureau, 30 Tower View, Kings Hill, Kent, ME19 4UY

The management system of Certificate Number 2033755

FANCO PRECISION (M) SDN. BHD.

38A-2 Lebuh Lapangan Siber 2, Bandar Cyber, 31350 Ipoh, Perak

has been assessed and certified as meeting the requirements of

ISO 9001:2015

for the following activities

- Trading, Installation, Commission, Service And Maintenance Of Semiconductor Equipments.
 - 2. Provision Of Machining Services For Metal Parts

Further derifications regarding the scope of this contilicate and the applicability of requirements may be obtained by consulting the certifie

Valid from
Initial Certification: 26 March 2021
Latest Issue: 26 March 2022
Expiry Date: 25 March 2024
subject to annual assessments

Authorised by

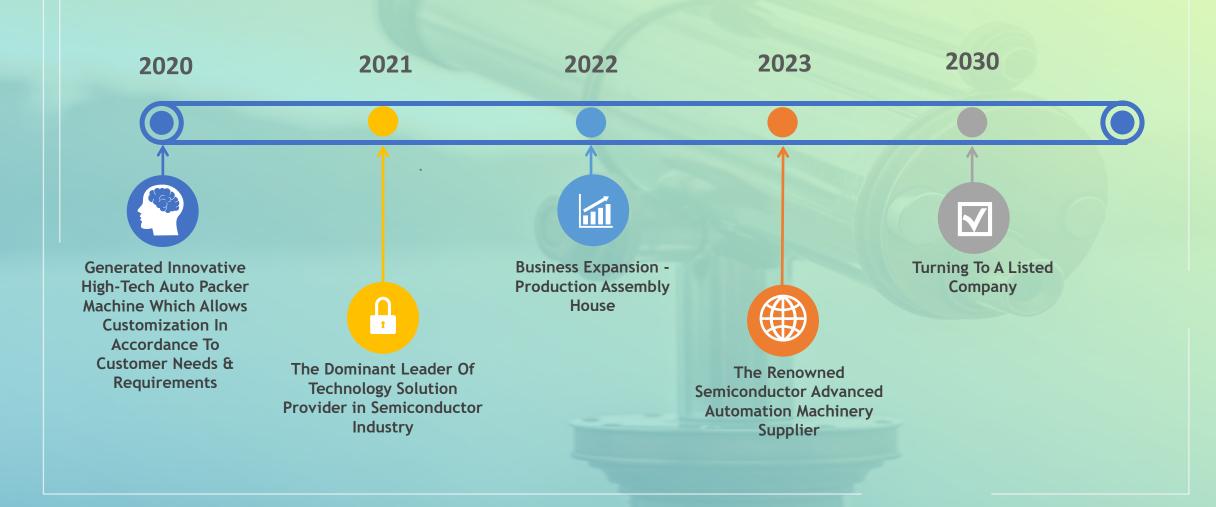


Mike Tims Chief Executive Officer

www.british-assessment.co.uk



OUR BUSINESS ROADMAP



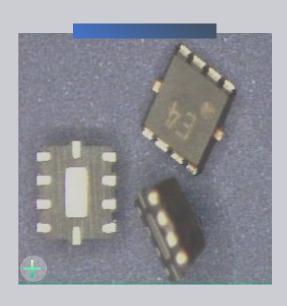
Authorized Partner Of SSOTRON Korea



Semiconductor Automation System & Accessories

Authorized Partner of SSOTRON Korea

(www.ssotron.co.kr)







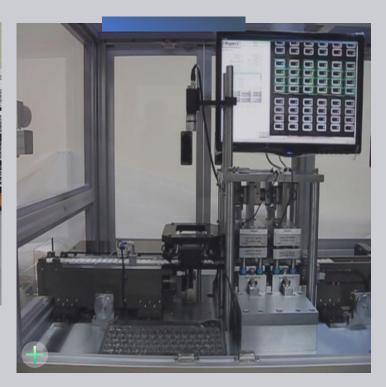
Semiconductor Automation System & Accessories

Authorized Partner of SSOTRON Korea

(www.ssotron.co.kr)







Fully Auto Trim / Form System

Fully Auto Trimming / Forming & Singulation System

Piercing And Cutting Tool With Vision



Semiconductor Automation System & Accessories

Authorized Partner of SSOTRON Korea

(www.ssotron.co.kr)







Module & Die Set

Tray Unloading System

Master Die Set With Tools

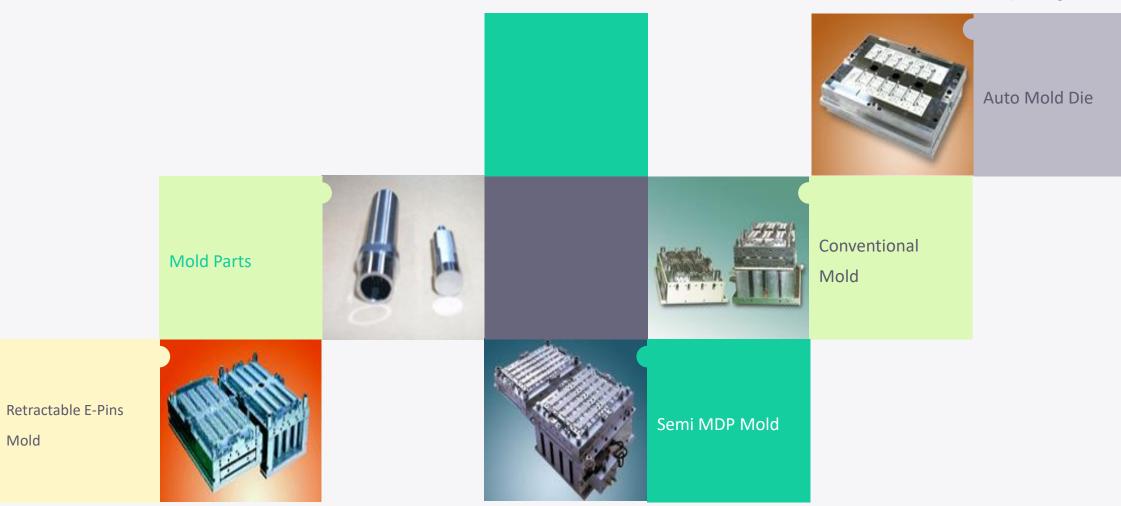


Authorized Partner Of GS Tech Co., Ltd



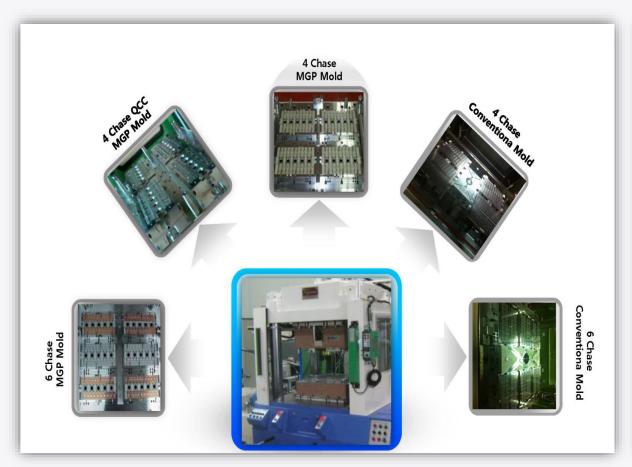
Mold Chase & Accessories

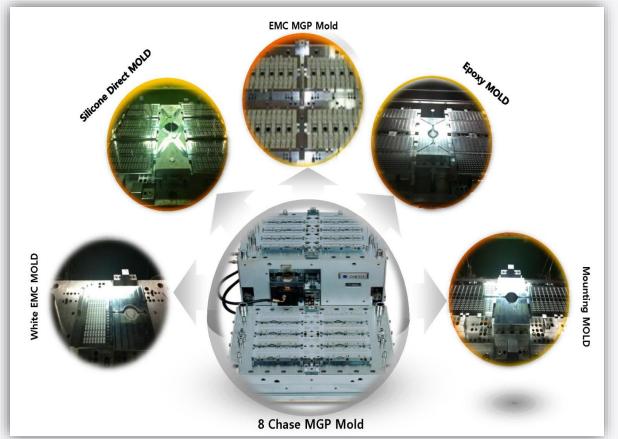
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Mold Chase & Accessories

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Mold Chase & Accessories

Authorized Partner of GS Tech Co. Ltd Korea (www.gstech.co.kr)









Retract + Vacuum Mold

- Apply to Module Package & LED
- Minimum void by vacuum equipment
 - Required high quality package
- Shot distance for isolation by retract equipment











Semi-M.G.P Mold

- Apply to discrete package (low cost pkg)
- Cost efficient compared to conventional mold
 - Improve quality by multi pot (2~4 pot)
 - Need to pre heater m/c







M.G.P Mold

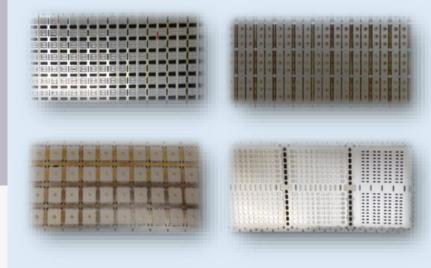
- Apply to small package like SOT, SC
- Equalize performance with auto mold
 - Used to mini tablet emc
- Molding flow same as auto mold



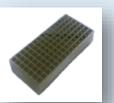
Auto Mold & Conversion Kit

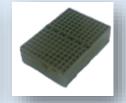
- Convert other device package Towa, Dai-ichi, Yamada, ASM systems
 - Low cost efficient convert price

E.D.M Polishing











Authorized Partner Of Shenzhen Tensun Precision Equipment Co., Ltd.





Authorized Partner of Shenzhen Tensun Precision Equipment Co., Ltd.

(http://en.tensun.cn/)



Standard high precision dispensing machine Sherpa91N



Dual station dispensing machine Sherpa83



Dual head dispensing machine Sherpa93



5-Axis linkage dispensing machine FD300

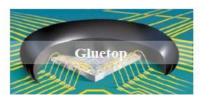
Application Processes

- Semiconductor system level packaging / advanced package dispensing
- SMT / PCB / FPC dispensing
- CCM / Vibrator / Speaker etc. precision parts dispensing and assembly
- · Mini-LED Lens / Dam / Fill dispensing
- · Curved screen dispensing & assembly















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(http://en.tensun.cn/)

				(http://en.tens
	Wafer	Substrate	Lead frame	Panel
Underfill	Sherpa91N +Piezo valve(Jetting)	Sherpa91N/900 +Piezo valve(Jetting)	-	Sherpa900 +Piezo valve(Jetting)
Dam & Fill	Sherpa91N +Piezo valve(Jetting)	Sherpa91N/900 +Piezo valve(Jetting)/Auger valve(Contact)	-	Sherpa900 +Piezo valve(Jetting)/Auger valve(Contac
Glob Top	-	Sherpa91N/900 +Piezo valve(Jetting)	Sherpa91N +Piezo valve(Jetting)	Sherpa900 +Piezo valve(Jetting)
Solder/Silver Dot Dispensing	Sherpa91N +Piezo valve(Customization for solder paste/Silver jetting)	Sherpa700 +Piezo valve(Customization for solder paste/Silver jetting)	Sherpa700 +Piezo valve(Customization for solder paste/Silver jetting)	Sherpa900 +Piezo valve(Customization for solder paste/Silver jetting)
Solder Line Dispensing	-	Sherpa83 +Dispensing controller(Contact)	-	-
Lid Attach	-	LA1200 +Auger valve(Contact)	-	-
Spray	Sherpa91N+Spray valve	-	Sherpa65+Spray valve	-
10 m		EL STATE OF THE ST		







Sherpa900



Sherpa65



Sherpa700



Sherpa83



LA1200

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(http://en.tensun.cn/)



Multi-function piezo jet valve JVS96



Solder ultramicro peristaltic dispensing valve MSS91



Screw dispensing valve SVS81





Volumetric dispensing valve SPP-H9

- Meet the requirements of Underfill, UV, Solder Paste, Silver Glue and other dispensing process
- Developed independently
- piezo jet valve , Solder ultramicro peristaltic dispensing valve , Screw dispensing valve , Volumetric dispensing valve etc.
- Minimum dispensing diameter is 100μm, Minimum dispensing volume is 0.5nl
- Dispensing accuracy 1mg±5%@CPK 1.33



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(http://en.tensun.cn/)



Auger Valve SVS81

Viscosity range: 20000~2000000cps

Maximum speed: 1200rpm

Glue accuracy: 5mg±5% CPK≥1.33



Piezo Valve JVS91

Viscosity range: 0~200000cps

Maximum jetting frequency: 1500Hz

Glue accuracy: 1mg±5% CPK≥1.66



Piezo valve JVS100

(Customization for solder paste/Silver dispensing)

Viscosity range: 20000~100000cps

Maximum jetting frequency: 300Hz

Glue accuracy: 3mg±5% CPK≥1.33



Spray valve TS-787

Viscosity range: 0~1000cps

Minimum line width: 3mm

Glue accuracy: 5mg±10% CPK≥1.33



Glue volume accuracy: ≤±0.0088ul

Volumetric metering valve SPP-H9

Viscosity range: 0~50000cps

Minimum volume resolution: 0.000177ul

Precision Dicing Products

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(http://en.tensun.cn/)







ADS2100 SDS1220 SDS1210



Precision Dicing Products

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(http://en.tensun.cn/)

Application: Wafer, QFN, MEMS, SIP, PCB, EMC, Wire Holder, Glass, Ceramics

Compatible with 8-12 round, 200x300 square processing sizes

High precision BBD detection function, minimum detection capacity of 0.5x0.5mm

High precision NCS height measurement, control accuracy within 2µm

Core vision and algorithms



Authorized Partner Of Shenzhen Shenkeda Semiconductor Technology Co., Ltd.



Test Handlers, Tray Taping & Auto Reel Change

Authorized Partner of Shenzhen Shenkeda Semiconductor Technology Co., Ltd

(https://en.szskd.com/)



Test Handler

Authorized Partner of Shenzhen Shenkeda Semiconductor Technology Co., Ltd

(https://en.szskd.com/)



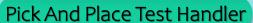




Turret Test Handler

Dual Track Test Handler









Gravity Test Handler

Tray Taping & Auto Reel Change Machine

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(https://en.szskd.com/)



Tray Taping Machine



Automatic Reel Change Machine

Authorized Partner of Precision Intelligent Technology Co., Ltd.





Die Attach Equipment

Authorized Partner of Precision Intelligent Technology Co., Ltd.

(www.precisioncn.com)

Solutions

Semiconductor Packaging

Photonics Packaging MiniLED Packaging Power Devices Packaging

SiC/GaN Packaging Memory Packaging Advanced Packaging

Inductor Winding

Products



IC Linear High Precision Die Attach



Ultra-high precision die attach



XBonder Ultra-high Speed Thorn Die Attach



Clip Bonder High-speed Clip Bonding System



Power Module Die Bonder



Thin Die Laminate Die Bonder



Flip Chip Die Bonder



High Precision Winding Machine

Core Functional Module





Linear Motor





Servo drive controller



Machine Vision



DA1201 IC Linear High Precision Die Attach

Authorized Partner of Precision Intelligent Technology Co., Ltd.

(www.precisioncn.com)

- Wafer size: 6"- 12";
- Dual dispensing system;
- High-precision linear driven bond head;
- Support DAF function;
- Multifunction work table, suitable for different kinds of lead frames & substrates;
- High-precision wafer table with highly accurate die rotation system and motorized wafer expansion system;
- Intelligent dispensing control system to realize precision glue volume control;
- Missing die detection and re-picking function;
- Programmable Pick / Bond Force;
- Customization for special design is also available.





DA1201FC Flip Chip And Die Attach

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(www.precisioncn.com)

- Specially designed for flip chip devices with low pin count, DA1201FC provides a fully automatic high-speed flip chip solution for various devices, such as SOIC, SO, QFN, BGA, LGA, etc. At the same time, it is equipped with die attach system;
- High-speed and high precision die bonding capability;
- MS Windows® operating system and flexible connectivity;
- Flip chip and die bonding in one machine the conversion between the two processes is simple and easy;
- Comprehensive inspection system;
- Excellent X/Y placement accuracy;
- Flip-chip mode/high-precision die attach mode: ±15μm@3σ;
- Die attach mode: ±25μm@3σ;
- High density lead frame handling capability.





DA801 IC Linear High Precision Die Attach

Authorized Partner of Precision Intelligent Technology Co., Ltd.

(www.precisioncn.com)

- Wafer size: 6" 8";
- Dual dispensing system;
- High-precision linear driven bond head;
- Support DAF function;
- Multifunction work table, suitable for different kinds of lead frames & substrates;
- High-precision wafer table with highly accurate die rotation system and motorized wafer expansion system;
- Intelligent dispensing control system to realize precision glue volume control;
- Missing die detection and re-picking function;
- Customization for special design is also available.



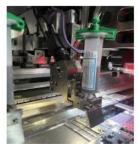


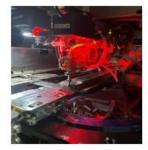
High Speed Clip Bonding System

Authorized Partner of Precision Intelligent Technology Co., Ltd.

(www.precisioncn.com)











One-stop clip bonding solution
• From die bonding, clip bonding to reflow process.

Innovative machine design

- o Patented bond head design.
- Array suction clip bonding process.
- Multi-head independent dispensing process.
- o Intelligent reflow process.
- Easy to use conversion.

Flexible configuration

- o 6-12" wafer.
- Support different die size





CB930 High Speed Clip Bonding Machine

Authorized Partner of Precision Intelligent Technology Co., Ltd.

(www.precisioncn.com)

- Placement accuracy: ±50μm @3σ, theta placement accuracy: ±3°@3σ;
- Up to 20Clips/ Cycle;
- Prebond & Posbond function;
- Solder patch & solder paste inspection function;
- High precision linear drive die bond head;
- High precision clip punching system;
- The multi dispensing independent control system provides more accurate glue control, equipped with glue detection, with automatic glue filling function;
- Multiple configurations meet various market demands, as well as customization according to special demands;
- Freely match various types of reflow equipment.





Authorized Partner Of TSP Co., Ltd.

MODULE PACKAGE



Module

■ ITEM: SCMF-1, SPIM 40,

APM, IPM, SPM

■ Material : Copper

Plating: Bare, Ni, Ni + Ag





POWER PACKAGE



Automotive Type

ITEM : TO-220/263-3L, TO-247-3L

• Material : Copper

• Plating : Bare, Ni, Ni + Ag



Commercial Type

Conventional

■ Item : TO-220-2/3L, TO-263-3L

TO-3P, TO-247, TO-3PF

Material : Copper

• Plating : Bare, Ni, Ni + Ag

Matrix

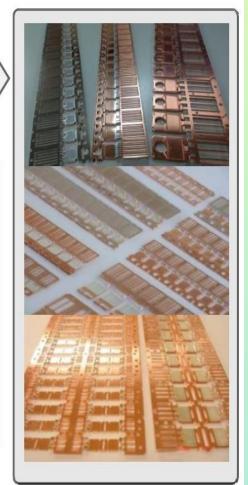
Item : D-Pak matrix, TO-252 (D/I-

PAK)

Material : CopperPlating : Bare, Ni

IDF

Item : TO-220Material : CopperPlating : Bare, Ni



Stamping & Etching L/F Housing

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SMALL PACKAGE



SMD

■ ITEM :TO-236, TO-243, SC89 / SOD523, SC70/SOD323, SOT490

Material: Alloy42,Copper

Plating : Cu, Ag, Cu + Ag, Spot Ag

Through Hole

■ ITEM : TO-92 Strip, Reel

Material : CopperPlating : Bare, Ag

IC/TANTAL PACKAGE



Integrated Circuit

ITEM : SOP8. SOP-14,16

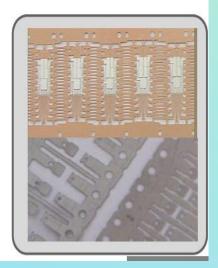
Material : CopperPlating : Ag (Spot)

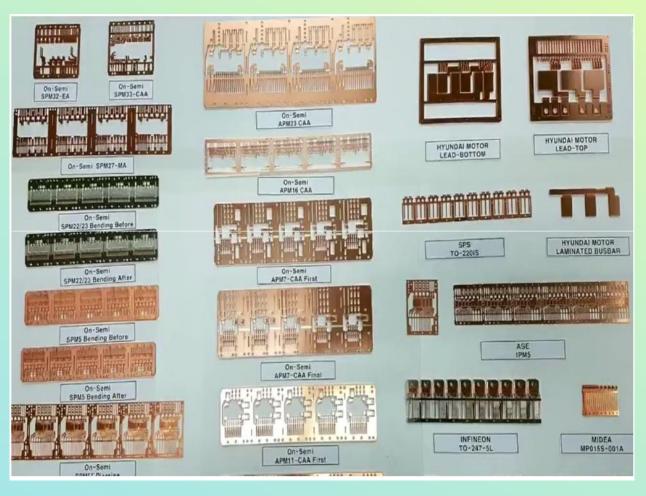
Tantal

■ ITEM : Tantal A, B, C, D, P, PS, J type

Material : Alloy42Plating : Sn, Ag





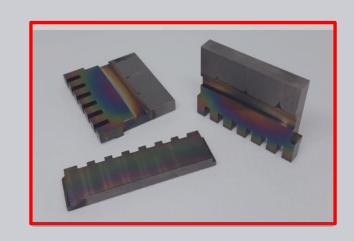


Samples of Experience Devices

High Precision Piece Parts











Auto Reel Packer Machine

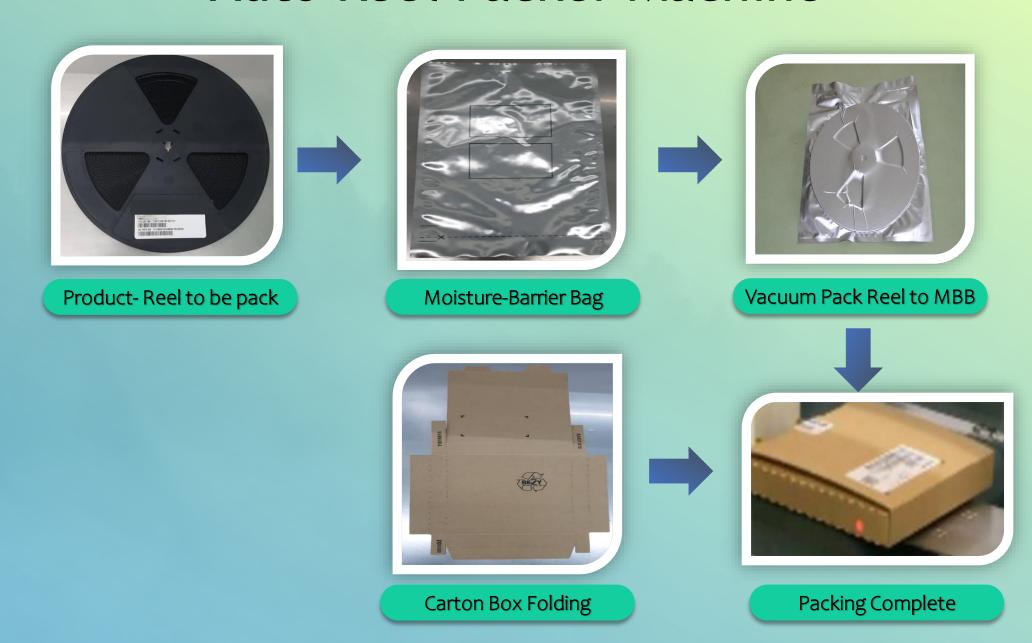


A brand new advanced auto packer machine, where thoughts and ideas are originated from the Director of FANCO PRECISION, allows you to flexibly customize your auto packer machine just right to your industrial needs and requirements!

This high-tech automation machine, aiming at innovation for new generation of smart industrial factory, significantly helps industries to move forward towards Industrial 4.0, but also empowers customers to become more sustainable, profitable across operations, maximize asset, and with higher production performance!

Auto-projects are currently on-going & it's a trend now in owing your unique automation machinery!

Auto Reel Packer Machine

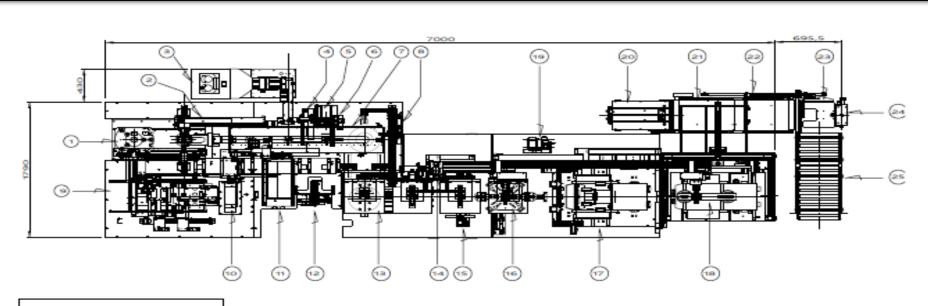


Auto Reel Packer Machine



HIC and Silica Gel to be insert into Moisture Barrier Bag (MBB)

Auto Reel Packer Machine Layout



AUTO PACKING MACHINE

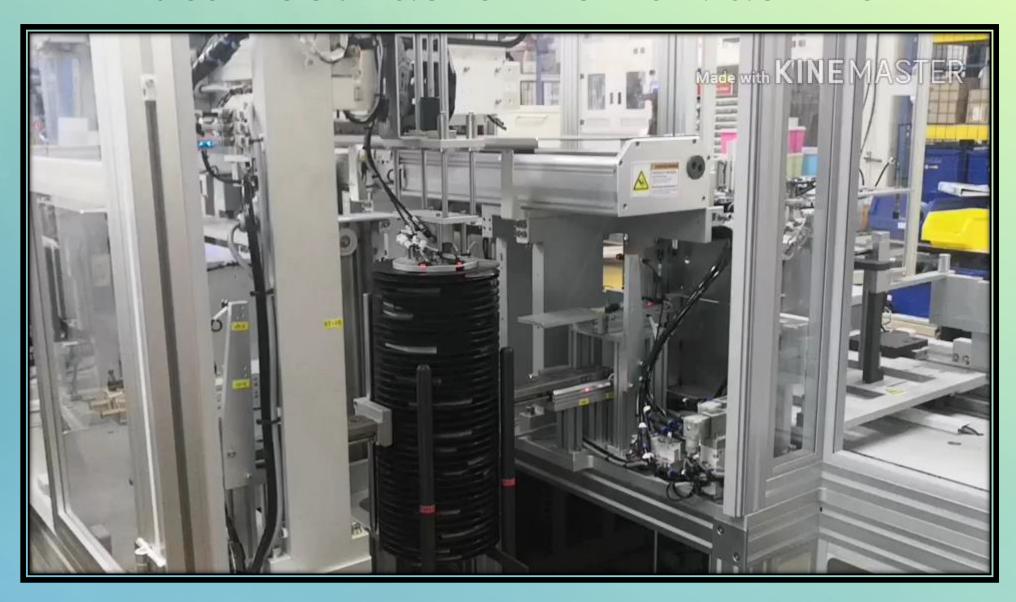
LEGEND

- 1) REEL LOADER (STACKED)
- 2) REEL PICK AND PLACE
- SELICA GEL LOADER
- SELICA GEL PICK AND PLACE
- HIC STICKER LOADER MAGAZINE
- HIC PICK AND PLACE
- REEL WALKING BEAM
- REEL INSERT PUSHER
- MBB LOADER WITH PICK & PLACE
- 10) MBB SINGULATE STATION
- LABEL PRINTER
- 12) LABEL DISPENSER
- REEL PUSH IN STATION WITH MBB

- 14) VACUUM & HEAT SEALING
- 15) MBB WITH REEL ROTATE MODULE
- 16) LEAK CHECK & PREFOLD STATION
- 17) BOX FOLDING STATION
- 18) CARTON BOX LOADER
- 19) LABEL PRINTER FOR FOLDED BOX
- 20) PRIMARY CONVEYOR FOR BOX LABELING
- 21) BOX OFFLOING CONVEYOR 22) BOX OFF LOADING PUSHER
- 23) BOX STACKED UP OFF LOAD PUSHER 24) STACKED BOX ELEVATOR

 - 25) FINISHED GOODS OFF LOAD CONVEYOR

Auto Reel Packer Demo Machine





FANCO PRECISION (M) SDN BHD

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